



REPLACEMENT SHEET
Multi-Layered Barrier Metal Thin Films for Cu Interconnect by ALCVD
Serial No.: 09/819,296
Pan et al.
1/3

Fig. 1

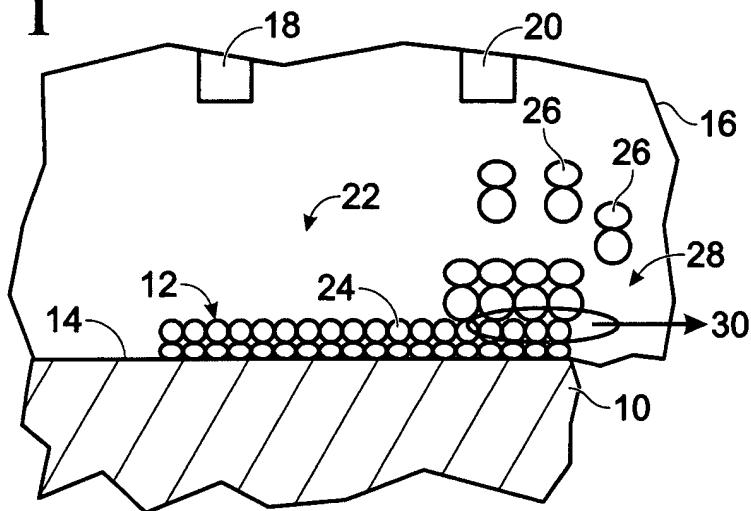


Fig. 2

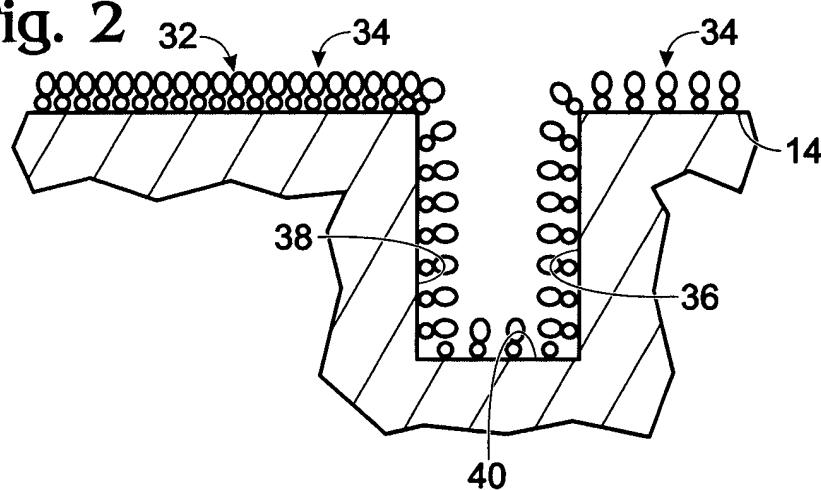


Fig. 3

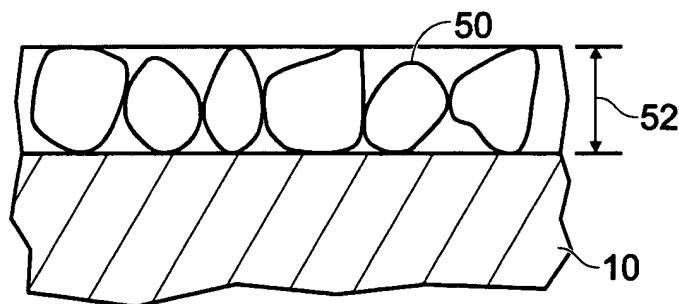


Fig. 4

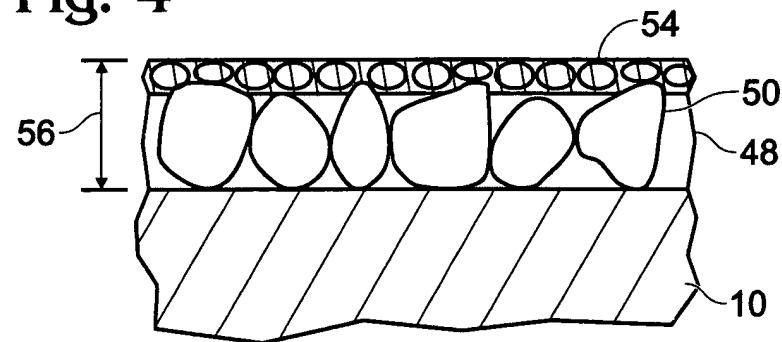


Fig. 5

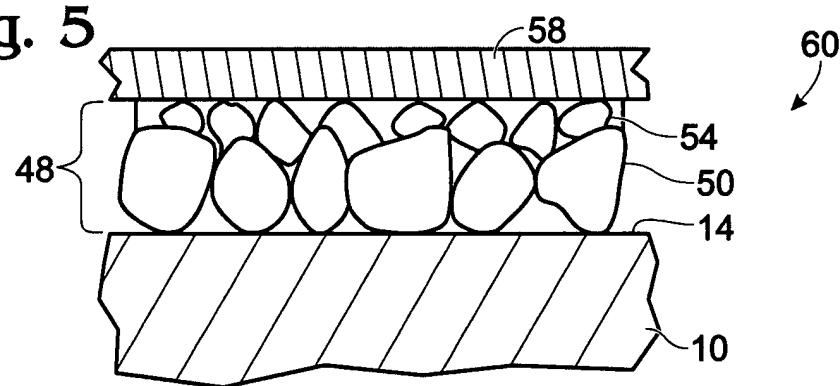


Fig. 6

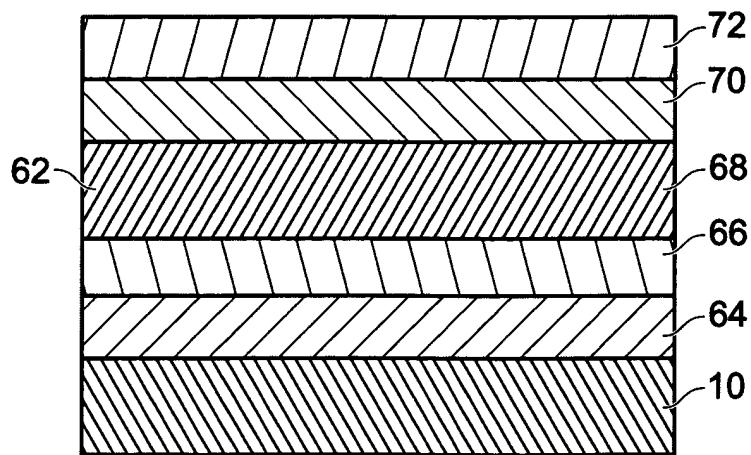


Fig. 7

